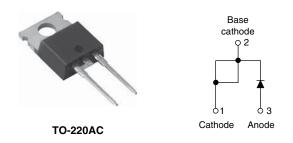
# VS-8ETH03PbF, VS-8ETH03-N3

**Vishay Semiconductors** 



# Hyperfast Rectifier, 8 A FRED Pt<sup>®</sup>



PRODUCT SUMMARY								
Package	TO-220AC							
I <sub>F(AV)</sub>	8 A							
V <sub>R</sub>	300 V							
V <sub>F</sub> at I <sub>F</sub>	0.83 V							
t <sub>rr</sub> typ.	See Recovery table							
T <sub>J</sub> max.	175 °C							
Diode variation	Single die							

### **FEATURES**

- · Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- · Designed and qualified according to JEDĔC<sup>®</sup>-JESD 47



RoHS

COMPLIANT

HALOGEN

FREE

#### Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### **DESCRIPTION / APPLICATIONS**

300 V series are the state of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diodes in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Repetitive peak reverse voltage	V <sub>RRM</sub>		300	V					
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 155 °C	8	٨					
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>C</sub> = 25 °C	100	A					
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C					

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	I <sub>R</sub> = 100 μA	300	-	-				
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 8 A	-	1.0	1.25	V			
		I <sub>F</sub> = 8 A, T <sub>J</sub> = 125 °C	-	0.83	1.00				
	age current I <sub>R</sub>	$V_R = V_R$ rated	-	0.02	20				
Reverse leakage current		$T_J = 125 \text{ °C}, V_R = V_R \text{ rated}$	-	6.0	200	μA			
Junction capacitance	on capacitance C <sub>T</sub> V <sub>R</sub> = 300 V		-	31	-	pF			
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8	-	nH			

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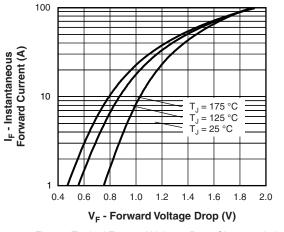


<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_C = 25$ °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS				
Reverse recovery time	t <sub>rr</sub>	$I_F = 1 \text{ A}, \text{ d}I_F/\text{d}t = -3$	-	-	35					
		T <sub>J</sub> = 25 °C		-	27	-	ns			
		T <sub>J</sub> = 125 °C		-	40	-				
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 8 A dI <sub>F</sub> /dt = - 200 A/μs V <sub>B</sub> = 200 V	-	2.2	-	٨			
		T <sub>J</sub> = 125 °C		-	5.3	-	A			
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	30	-	nC			
		T <sub>J</sub> = 125 °C		-	106	-	nC			

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C				
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	1.45	2.5					
Thermal resistance, junction to ambient per leg	R <sub>thJA</sub>	Typical socket mount	-	-	70	°C/W				
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.2	-					
Waight			-	2.0	-	g				
Weight			-	0.07	-	oz.				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)				
Marking device	Marking device Case style TO-220AC 8ETH03									

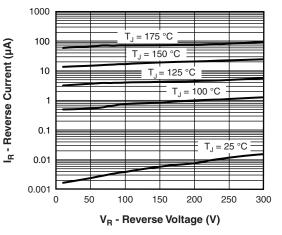
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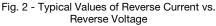
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Fig. 1 - Typical Forward Voltage Drop Characteristics





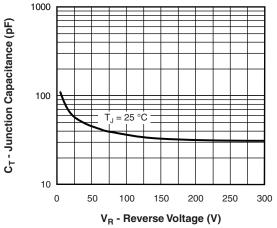


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

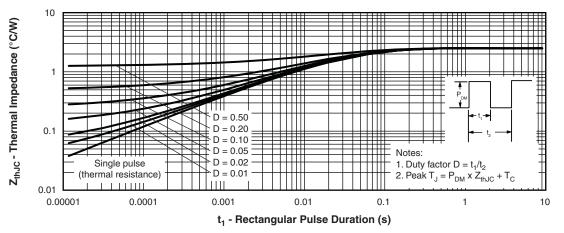


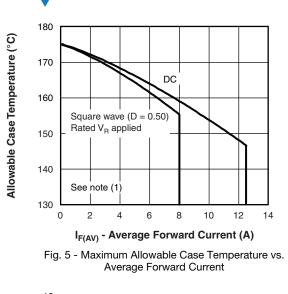
Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

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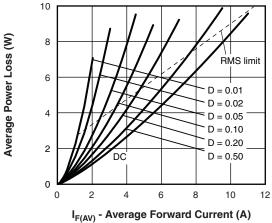
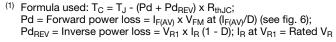


Fig. 6 - Forward Power Loss Characteristics

#### Note



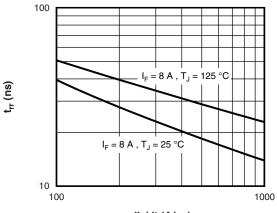
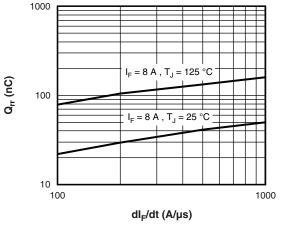




Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt





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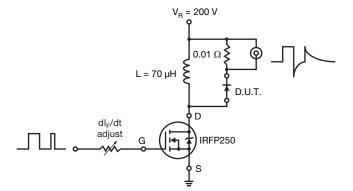
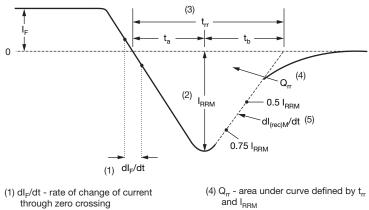


Fig. 9 - Reverse Recovery Parameter Test Circuit



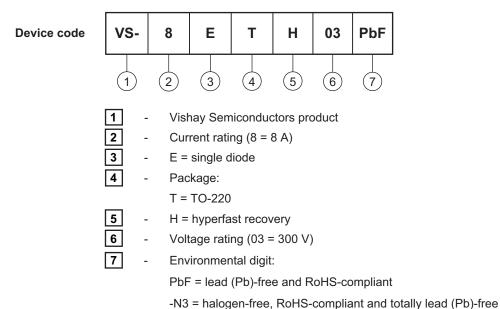
through zero crossing

- (2) I<sub>RRM</sub> peak reverse recovery current
- (3) t<sub>rr</sub> reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75  $I_{\text{RRM}}$  and 0.50  $I_{\text{RRM}}$  extrapolated to zero current.
- $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (5) dI\_{(rec)M}/dt peak rate of change of current during  $t_{\rm b}$  portion of  $t_{\rm rr}$
- Fig. 10 Reverse Recovery Waveform and Definitions



### **ORDERING INFORMATION TABLE**

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 ORDERING INFORMATION (Example)

 PREFERRED P/N
 QUANTITY PER T/R
 MINIMUM ORDER QUANTITY
 PACKAGING DESCRIPTION

 VS-8ETH03PbF
 50
 1000
 Antistatic plastic tube

 VS-8ETH03-N3
 50
 1000
 Antistatic plastic tube

LINKS TO RELATED DOCUMENTS								
Dimensions	www.vishay.com/doc?95221							
Part marking information	TO-220ACPbF	www.vishay.com/doc?95224						
Part marking information	TO-220AC-N3	www.vishay.com/doc?95068						



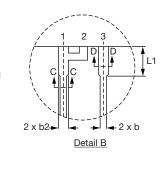
**TO-220AC** 

plane

### **DIMENSIONS** in millimeters and inches









**Diodes** 1 + 2 - Cathode 3 - Anode

Conforms to JEDEC outline TO-220AC

SYMBOL	MILLIN	IETERS	INC	HES	NOTES	SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	STWDOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.25	4.65	0.167	0.183		E1	6.86	8.89	0.270	0.350	6
A1	1.14	1.40	0.045	0.055		E2	-	0.76	-	0.030	7
A2	2.56	2.92	0.101	0.115		е	2.41	2.67	0.095	0.105	
b	0.69	1.01	0.027	0.040		e1	4.88	5.28	0.192	0.208	
b1	0.38	0.97	0.015	0.038	4	H1	6.09	6.48	0.240	0.255	6, 7
b2	1.20	1.73	0.047	0.068		L	13.52	14.02	0.532	0.552	
b3	1.14	1.73	0.045	0.068	4	L1	3.32	3.82	0.131	0.150	2
с	0.36	0.61	0.014	0.024		L3	1.78	2.13	0.070	0.084	
c1	0.36	0.56	0.014	0.022	4	L4	0.76	1.27	0.030	0.050	2
D	14.85	15.25	0.585	0.600	3	ØР	3.54	3.73	0.139	0.147	
D1	8.38	9.02	0.330	0.355		Q	2.60	3.00	0.102	0.118	
D2	11.68	12.88	0.460	0.507	6	θ	90° t	o 93°	90° t	o 93°	
E	10.11	10.51	0.398	0.414	3, 6						

Notes

<sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994

- <sup>(2)</sup> Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- <sup>(4)</sup> Dimension b1, b3 and c1 apply to base metal only
- <sup>(5)</sup> Controlling dimension: inches
- <sup>(6)</sup> Thermal pad contour optional within dimensions E, H1, D2 and E1
- <sup>(7)</sup> Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- <sup>(8)</sup> Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



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